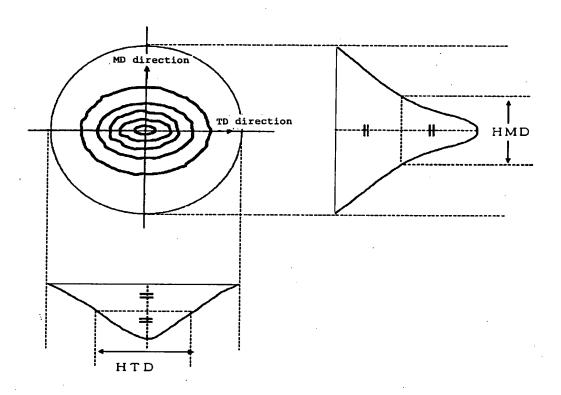
App No.: Not Yet Assigned Inventor: Masayuki TSUTSUMI et al. Title: POLYIMIDE FILM

FIG. 1

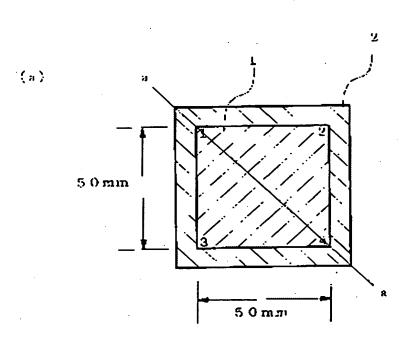
Docket No.: 358362011300

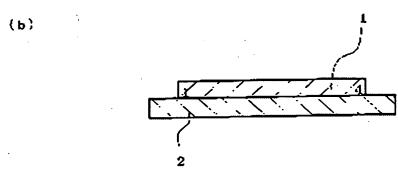


App No.: Not Yet Assigned Inventor: Masayuki TSUTSUMI et al. Title: POLYIMIDE FILM

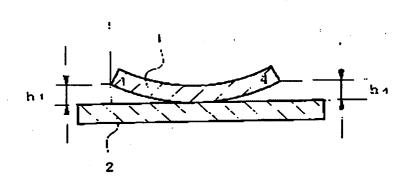
Docket No.: 358362011300

FIG. 2





(e)



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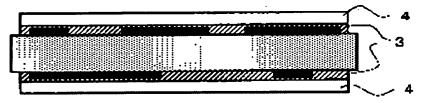
Title: POLYIMIDE FILM

## FIG. 3

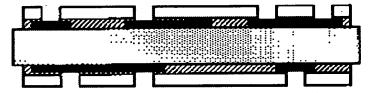
(a) core substrate



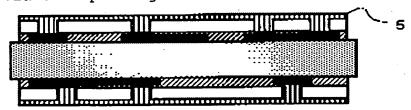
(b) first interlayer insulation layer formation



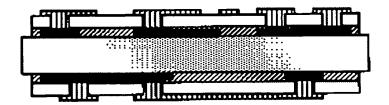
(c) via-hole perforation



(d) via fill plating

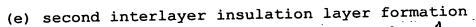


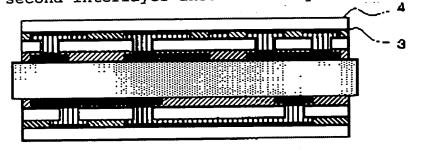
(e) first buildup layer pattern formation



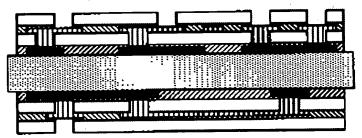
App No.: Not Yet Assigned Inventor: Masayuki TSUTSUMI et al. Title: POLYIMIDE FILM Docket No.: 358362011300

FIG. 4

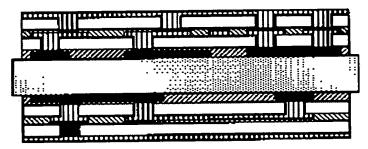




(b) via-hole perforation



(c) via fill plating



(d) second buildup layer pattern formation

